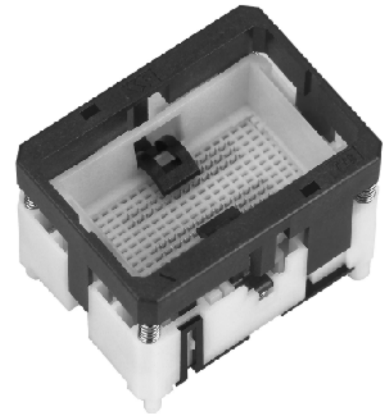
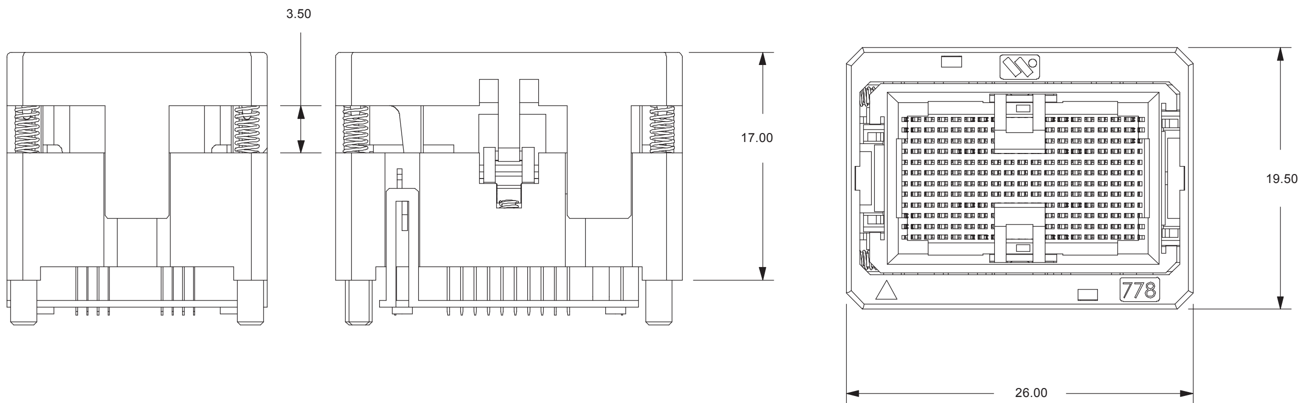
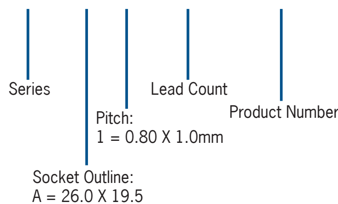
778 SERIES FBGA SOCKET

- Open Top
- Accommodates 0.80mm x 1.00mm pitch array
- Compact size and low actuation force
- Pitch/tweezer contact results in 4 points of interface per solder ball
- Unique mechanism to eliminate solder ball sticking
- Maximum package size is 11.0 x 18.5mm





DESCRIPTION & ORDERING INFORMATION



MATERIALS & SPECIFICATIONS

- Socket Body: PES, PEI, LCP or Equivalent
- Contact: Beryllium Copper Alloy
- Contact Plating: Gold or NiPd
- Contact Normal Force: 10~13 grams per pin
- Contact Current Rating: 0.5 amps
- Contact Resistance: 100 mΩ max
- Dielectric: 700V AC for 1 min.
- Insulation Resistance: 1,000 MΩ @ 500V DC
- Temperature Rating: 150°C
- Durability: 10,000 cycles

Pitch e (mm)	Ball Count	Package Size	Matrix Contact	Ball Dia. (mm)	Ball Height (mm)	Contact Plating	Part Number	Socket Outline (mm)
0.80 X 1.0	55	11 X 18.5	12 X 18	0.35	0.24	Au	778A1055-101	19.5 x 26
	55	11 X 18.5	12 X 18	0.51	0.39	Au	778A1055-102	19.5 x 26
	144	11 X 18.5	12 X 18	0.35	0.24	Au	778A1144-101	19.5 x 26
	144	11 X 18.5	12 X 18	0.51	0.39	Au	778A1144-102	19.5 x 26

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